IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typp http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier Inforn	nation															
Company name* Company uniq				que ID			Unique ID Authority					Response Date*				
onsemi												2024-05-16				
Contact Name		Title - Contact			F	Phone - Contact*					Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance			1	NA NA					Product-Env-Stewards@onsemi.com					
uthorized Represe	Title - Representative			F	Phone - Representative*				Email - Representative*							
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Request	er Item Number Mfr Item		m Number Mfr Item Name				Effective Da	te Version Manufacturing Site		uring Site	Weight*		*	UOM	Unit Type	
		NCV78763DQ0AR2G PWR LED version of 0			ED BST/2BCK 1.6A/60V Gresham of 0L763-001-FTP		2024-05-16			BE4		5	510.08 mg		mg	Each
Ianufacturing	Process Information	on														
Terminal	Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MSL F	STD-020 MSL Rating		Peak Process Body Te		erature Max Time at Peak		Temperatu	Temperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		С	30 seco		secono	ls 3			
Comments																
TTENTION: MS	L 3 Rated item requires l	Bake and D	ry Pack (after	electrical test)												
or more informati	on regarding material co	mposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	10.62	mg	Supplier	Silicon (Si)	7440-21-3		10.62	mg
Die Attach	2.86	mg		Epoxy resin	proprietary data		0.286	mg
			Supplier	Silver (Ag)	7440-22-4		2.288	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.286	mg
Lead Frame	172.4	mg	Supplier	Zinc (Zn)	7440-66-6		0.1724	mg
			Supplier	Iron (Fe)	7439-89-6		3.9652	mg
			Supplier	Copper (Cu)	7440-50-8		168.09	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1724	mg
Mold Compound-Black	322.04	mg		Epoxy resin	proprietary data		16.102	mg
			Supplier	Phenolic Resin	Proprietary Data		6.4408	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		8.051	mg
			Supplier	Carbon Black (C)	1333-86-4		1.6102	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		289.836	mg
Plating	1.62	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			В	Nickel (Ni)	7440-02-0		1.4599	mg
			Supplier	Gold (Au)	7440-57-5		0.08	mg
Wire Bond - Au	0.54	mg	Supplier	Gold (Au)	7440-57-5		0.54	mg